EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	148	(solder) same (powder) same (volume or "vol.") near2 (percent $4 or percentage or "%")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:52
L2	79	1 and (flux)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:52
L3	80	1 and (flux$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:52
L4	17	(US-20040190252-$ or US-20040016995-$ or US-20040227236-$ or US-20100038123-$ or US-20090289101-$ or US-20050093153-$ or US-20030121564-$).did. or (US-6454159-$ or US-6189771-$ or US-6736907-$ or US-6641679-$ or US-5834848-$ or US-5869904-$ or US-6111322-$ or US-6122177-$ or US-6166433-$).did. or (JP-2003264259-$).did.	US-PGPUB; USPAT; DERWENT	ADJ	ON	2011/09/28 15:53
L5	300	("3871015" | "4684544" | "4921550" | "5012502" | "5040281" | "5216278" | "5233504" | "5276289" | "5355019" | "5371404" | "5417771" | "5455457" | "5473512" | "5485949" | "5533256" | "5535101" | "5569960" | "5585671" | "5598036" | "5640051" | "5641996" | "5658827" | "5705850" | "5729440" | "5731630" | "5751060" | "5762258" | "5764485" | "5773888" | "5804248" | "5866951" | "5877079" | "5878943" | "5904782" | "5905636" | "5932345" | "5950908" | "5953592" | "5973337" | "5973406" | "5985695" | "5989362" | "5990545" | "6025258" | "6030889" | "6059894" | "6090301" | "6132543" | "6189771" | "Re35423").PN. OR ("2003/0121564" | "2004/0016995" | "2004/0190252" | "2004/0227236" | "2005/0093153" | "2009/0289101" | "2010/0038123" | "5834848" | "5869904" | "6111322" |	US-PGPUB; USPAT; USOCR	ADJ	ON	2011/09/28 15:53

		"6122177" | "6166433" | "6189771" | "6454159" | "6641679" | "6736907").URPN.				
L6	1273	(228/214,215,256).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2011/09/28 15:56
L7	179	6 and (powder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:56
L8	70	7 and (volume or vol or "vol.")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:56
S1	1	("20080048009").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/17 09:59
S2	4	(("6189771") or ("6680128") or ("6951666") or ("5837119")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/17 10:05
S3	99	(particle or particulate or powder) with (flake) with solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:09
S4	17	(resin or epoxy) with (coat$3 or layer or film) same (particle or particulate or powder) with (flake) same solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:21
S5	67	(resin or epoxy or polymer$3) with (flake) with (metal$4) same solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:28
S6	13513	(resin or epoxy or polymer$3) with (coat$3 or layer or film) with (solder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:45
S7	75	S6 same (flake or flat) with (metal$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:46
S8	2641	bent with circuit board same (solder$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:09
S9	82	bent with circuit board same (solder$3) ball	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:09
S10	21	bent with component same (solder$3) ball	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:11
S11	528	(various or different) with (siz$3 or diameter) with (solder$3 near (ball or bump))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:12
S12	200	(various or different) with (siz$3 or diameter) with (solder$3 near (ball or bump)) same substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:12
S13	3	("2004/0227236").URPN.	USPAT	ADJ	ON	2011/01/25 20:15

S14	36	(bent or curv$3) with component same (solder$3) ball	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:19
S15	50	(warp$3) with component same (solder$3) ball	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:22
S16	15	"6189771"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:35
S17	10	("20040177997" | "5234149" | "5672542" | "6121062" | "6189771" | "6297560" | "6495397" | "6566234" | "7244634").PN. OR ("7632710").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2011/01/25 20:36
S18	15	"6189771"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:40
S19	591	flux same (iminodiaceteic acid or $3hydroxybenzoic acid or $3phenylalanine or mesaconic acid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:46
S20	59	flux with (iminodiaceteic acid or $3hydroxybenzoic acid or $3phenylalanine or mesaconic acid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:47
S21	1	("6,680,128").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2011/01/26 16:14
S22	63	flux same ($4hydroxy$1benzoic near acid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 16:22
S23	2	"20080048009"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 16:53
S24	13067	solder (bump or ball) same (electrodes)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 17:02
S25	1292	solder (bump or ball) same (electrodes) same(bga)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 17:03
S26	1292	solder (bump or ball) same (electrodes) same (bga)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 17:03
S27	105	(bga or semiconductor) same (solder near2 (ball or bump)) with (various or different) near2 (size or diameter)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 17:24

| S28 | 1 | "10585729" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/26 19:02 |

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	4156	((228/111.5,208,262.45,214,215,256) or (438/612)).CCLS.	US-PGPUB; USPAT; UPAD	OR	OFF	2011/09/28 16:18
L10	0	9 and ((solder$3) and (method or process) and (electrode) and (melt$4) and (coat$3 or layer or film $3) with (paste) and (resin) and (flake or oblong or oval) near2 (shap$4) and (core near2 metal) and (solidif$4)).clm.	US-PGPUB; USPAT; UPAD	ADJ	ON	2011/09/28 16:20

9/28/2011 4:20:55 PM
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